INTEGRATED CIRCUITS

DATA SHEET

74LV03Quad 2-input NAND gate

Product specification Supersedes data of 1997 Mar 28 IC24 Data Handbook





Quad 2-input NAND gate

74LV03

FEATURES

- Wide operating voltage: 1.0 to 5.5V
- Optimized for Low Voltage applications: 1.0 to 3.6V
- Accepts TTL input levels between V_{CC} = 2.7V and V_{CC} = 3.6V
- Typical V_{OLP} (output ground bounce) < 0.8V @ V_{CC} = 3.3V, $T_{amb} = 25^{\circ}C$
- Typical V_{OHV} (output V_{OH} undershoot) > 2V @ V_{CC} = 3.3V, $T_{amb} = 25^{\circ}C$
- Level shifter capability
- Output capability: standard (open drain)
- I_{CC} category: SSI

DESCRIPTION

The 74LV03 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT03.

The 74LV03 provides the 2-input NAND function.

The 74LV03 has open-drain N-transistor outputs, which are not clamped by a diode connected to $V_{\mbox{\footnotesize CC}}.$ In the OFF–state, i.e. when one input is LOW, the output may be pulled to any voltage between GND and V_{Omax}. This allows the device to be used as a LOW-to-HIGH or HIGH-to-LOW level shifter. For digital operation and OR-tied output applications, these devices must have a pull-up resistor to establish a logic HIGH level.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PZL} /t _{PLZ}	Propagation delay nA, nB to nY	C _L = 15pF V _{CC} = 3.3V	8	ns
C _I	Input capacitance		3.5	pF
C _{PD}	Power dissipation capacitance per gate	Notes 1, 2	4	pF

NOTES:

- C_{PD} is used to determine the dynamic power dissipation (P_D in μ W) P_D = C_{PD} × V_{CC}² x f_i + Σ (C_L × V_{CC}² × f_o) where: f_i = input frequency in MHz; C_L = output load capacitance in pF; f_o = output requency in MHz; V_{CC} = supply voltage in V;

 - Σ (C_L × V_{CC}² × f_o) = sum of the outputs. The condition is V_I = GND to V_{CC}
- 3 The given value of C_{PD} is obtained with : $C_L = 0$ pF and $R_L = \infty$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
14-Pin Plastic DIL	-40°C to +125°C	74LV03 N	74LV03 N	SOT27-1
14-Pin Plastic SO	-40°C to +125°C	74LV03 D	74LV03 D	SOT108-1
14-Pin Plastic SSOP Type II	–40°C to +125°C	74LV03 DB	74LV03 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +125°C	74LV03 PW	74LV03PW DH	SOT402-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 4, 9, 12	1A to 4A	Data inputs
2, 5, 10, 13	1B to 4B	Data inputs
3, 6, 8, 11	1Y to 4Y	Data outputs
7	GND	Ground (0V)
14	V _{CC}	Positive supply voltage

FUNCTION TABLE

INP	JTS	OUTPUT
nA	nB	nY
L	L	Z
L	Н	Z
Н	L	Z
Н	Н	L

NOTES:

H = HIGH voltage level

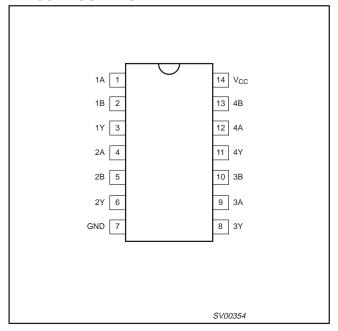
L = LOW voltage level

Z = High impedance OFF-state

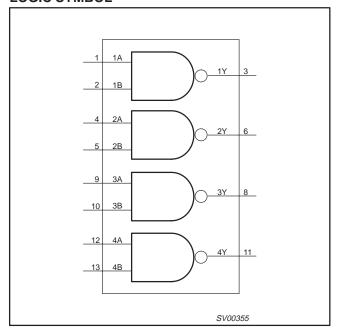
Quad 2-input NAND gate

74LV03

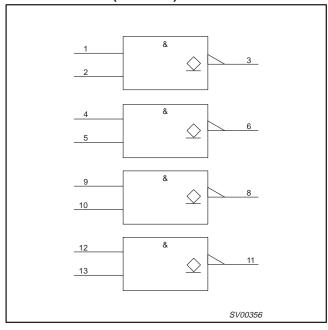
PIN CONFIGURATION



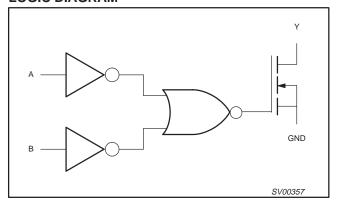
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



Quad 2-input NAND gate

74LV03

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{CC}	DC supply voltage	See Note1	1.0	3.3	5.5	V
VI	Input voltage		0	_	V _{CC}	V
Vo	Output voltage		0	-	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.0V \text{ to } 2.0V$ $V_{CC} = 2.0V \text{ to } 2.7V$ $V_{CC} = 2.7V \text{ to } 3.6V$ $V_{CC} = 3.6V \text{ to } 5.5V$		 - -	500 200 100 50	ns/V

NOTES:

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134)

Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
±I _{IK}	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5V$	20	mA
±lok	DC output diode current	$V_{O} < -0.5 \text{ or } V_{O} > V_{CC} + 0.5V$	50	mA
±ΙΟ	DC output source or sink current – standard outputs	$-0.5V < V_O < V_{CC} + 0.5V$	25	mA
±I _{GND} , ±I _{CC}	DC V _{CC} or GND current for types with –standard outputs		50	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package -plastic DIL -plastic mini-pack (SO) -plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: -40 to +125°C above +70°C derate linearly with 12mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

NOTES:

¹ The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 5.5V.

¹ Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

² The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

Quad 2-input NAND gate

74LV03

DC CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

					LIMITS	_		 _{UNIT}
SYMBOL	PARAMETER	TEST CONDITIONS	-40	°C to +8	5°C	-40°C to	+125°C	UNIT
			MIN	TYP ¹	MAX	MIN	MAX	1
		V _{CC} = 1.2V	0.9			0.9		
V_{IH}	HIGH level Input	V _{CC} = 2.0V	1.4			1.4]
VIН	voltage	V _{CC} = 2.7 to 3.6V	2.0			2.0		1 °
		V _{CC} = 4.5 to 5.5V	0.7*V _{CC}			0.7*V _{CC}		1
		V _{CC} = 1.2V			0.3		0.3	
V_{IL}	LOW level Input	$V_{CC} = 2.0V$			0.6		0.6] _/
۷IL	voltage	V _{CC} = 2.7 to 3.6V			0.8		0.8] `
		V _{CC} = 4.5 to 5.5			0.3*V _{CC}		0.3*V _{CC}	
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$		1.2				
	LUCLUS of subset	$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	1.8	2.0		1.8		
V_{OH}	HIGH level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	2.5	2.7		2.5		V
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu A$	2.8	3.0		2.8]
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	4.3	4.5		4.3		
V _{OH}	HIGH level output voltage;	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 6\text{mA}$	2.40	2.82		2.20		V
VОН	STANDARD outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 12\text{mA}$	3.60	4.20		3.50		ľ
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0				
	LOW level output	$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
V_{OL}	voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	V
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
V _{OL}	LOW level output voltage;	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 6\text{mA}$		0.25	0.40		0.50	
VOL	STANDARD outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 12\text{mA}$		0.35	0.55		0.65	ľ
I_{OZ}	HIGH level output leakage current	V_{CC} = 2.0 to 3.6V; V_I = V_{IL} ; V_O = V_{CC} or GND			5.0		10	μΑ
I _{OZ}	HIGH level output leakage current	$V_{CC} = 2.0 \text{ to } 3.6\text{V}; V_I = V_{IL};$ $V_O = 6.0\text{V}^2$			10		20	μА
I _I	Input leakage current	$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND			1.0		1.0	μА
Icc	Quiescent supply current; SSI	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}; I_O = 0$			20.0		40	μА
ΔI_{CC}	Additional quiescent supply current per input	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.6V$			500		850	μА

5

NOTES:

¹ All typical values are measured at T_{amb} = 25°C. 2 The maximum operating output voltage (V_{O(max)}) is 6.0V.

Quad 2-input NAND gate

74LV03

AC CHARACTERISTICS FOR 74LV03

GND = 0V; $t_r = t_f \le 2.5 \text{ns}$; $C_L = 50 \text{pF}$; $R_L = 1 \text{K}\Omega$

SYMBOL PARAMETER	WAVEFORM	CONDITION	_	LIMITS 40 to +85 °	С		ITS ⊦125 °C	UNIT					
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX					
t _{PZL} /t _{PLZ} Propagation delay nA, nB, to nY		1.2	_	50	_	_	_						
			2.0	_	17	26	_	31					
	nA, nB, to nY Figures, 1, 2	nA, nB, to nY	nA. nB. to nY	Figures, 1, 2	Figures, 1, 2	Figures, 1, 2	2.7	_	13	19	_	23	ns
			3.0 to 3.6	_	10 ²	16	_	19					
			4.5 to 5.5	_	_3	13	_	16					

NOTE:

- 1 Unless otherwise stated, all typical values are at T_{amb} = 25°C.
- 2 Typical value measured at $V_{CC} = 3.3V$.
- 3 Typical value measured at $V_{CC} = 5.0V$.

AC WAVEFORMS

 V_{M} = 1.5V at $V_{CC} \, \geq \, 2.7V \, \leq \, 3.6V$

 V_{M} = 0.5V * V_{CC} at $V_{CC} <$ 2.7V and \geq 4.5V

 $\ensuremath{\text{V}_{\text{OL}}}$ and $\ensuremath{\text{V}_{\text{OH}}}$ are the typical output voltage drop that occur with the output load.

 V_X = V_{OL} + 0.3V at V_{CC} \geq 2.7V and \leq 3.6V

 V_X = V_{OL} + 0.1 * V_{CC} at V_{CC} < 2.7V and \geq 4.5V

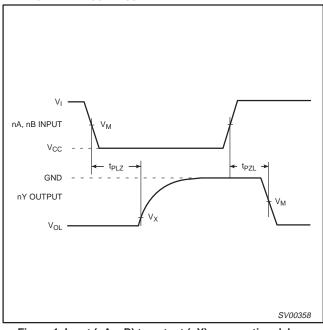


Figure 1. Input (nA, nB) to output (nY) propagation delays.

TEST CIRCUIT

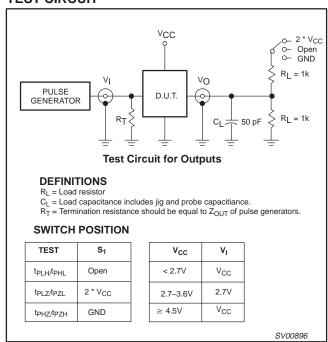


Figure 2. Load circuitry for switching times

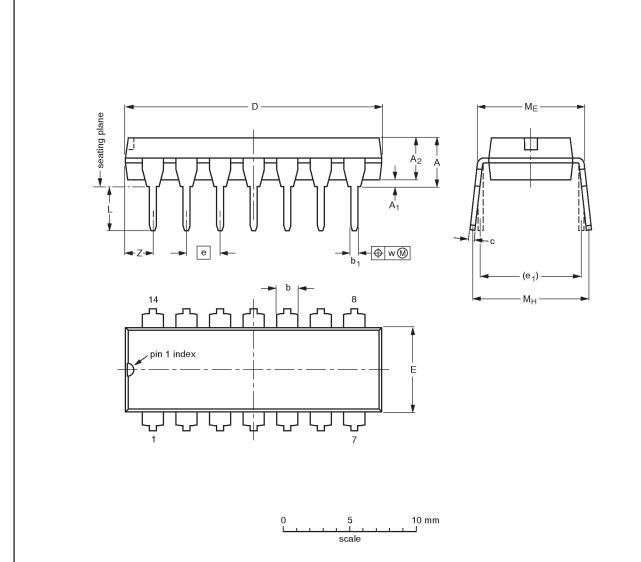
1998 Apr 20 6

Quad 2-input NAND gate

74LV03

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
OUTLINE VERSION SOT27-1	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	ı
SOT27-1	050G04	MO-001AA			92-11-17 95-03-11	

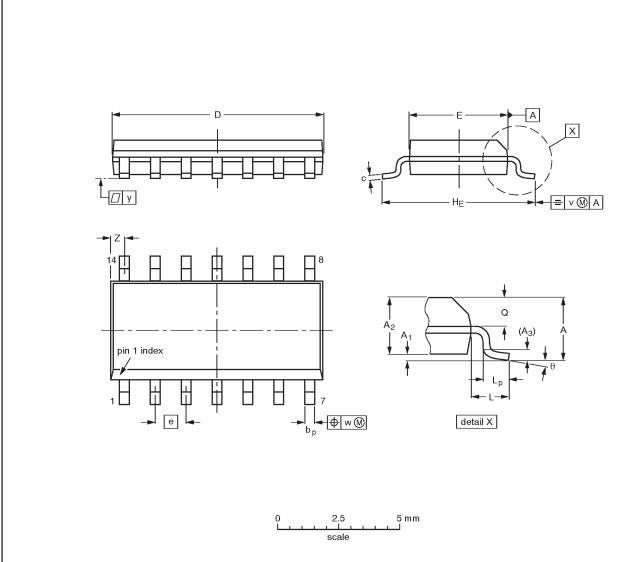
1998 Apr 20 7

Quad 2-input NAND gate

74LV03

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	1 // //60	0.0098 0.0039		0.01		0.0098 0.0075	0.35 0.34	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

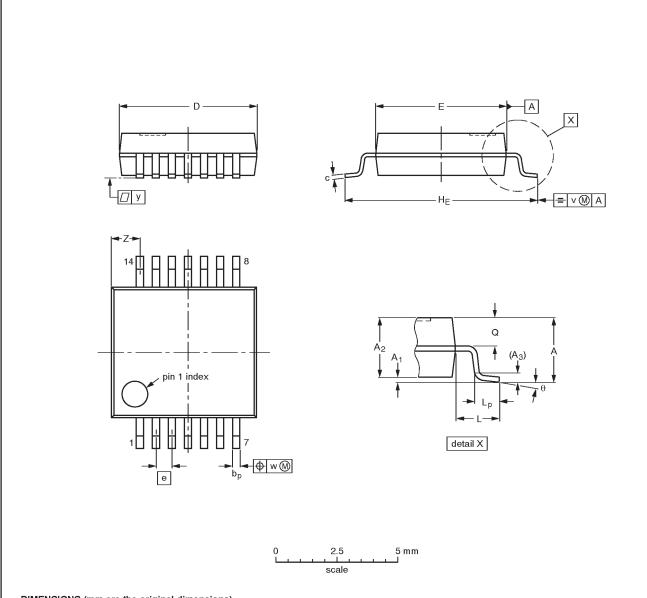
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
OUTLINE VERSION SOT108-1	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT108-1	076E06\$	MS-012AB			91-08-13 95-01-23	

Quad 2-input NAND gate

74LV03

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

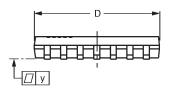
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VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT337-1		MO-150AB			-95-02-04 96-01-18

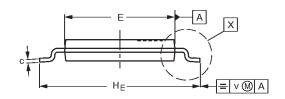
Quad 2-input NAND gate

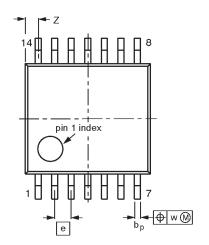
74LV03

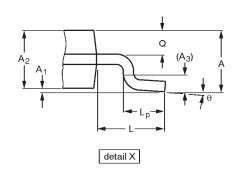
TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

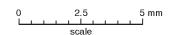
SOT402-1











DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT402-1		MO-153			94-07-12 95-04-04

1998 Apr 20 10

Quad 2-input NAND gate

74LV03

NOTES

Quad 2-input NAND gate

74LV03

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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